

DC ELECTRICAL CHARACTERISTICS: Unless otherwise stated, these specifications apply for $T_A = 0^\circ\text{C}$ to $+70^\circ\text{C}$; $V_{CC} = 5\text{V} \pm 5\%$, Input Common Mode Range $\pm 7\text{V}$, $T_A = T_J$.

PARAMETER	SYMBOL	TEST CONDITIONS	UC5181C		UNITS	
			MIN	MAX		
DC Input Resistance	R_{IN}	$3\text{V} \leq V_{IN} \leq 25\text{V}$	3	7	$k\Omega$	
Failsafe Output Voltage	V_{OFS}	Inputs Open or Shorted Together, or One Input Open and One Grounded	$0 \geq I_{OUT} \leq 8\text{mA}$, $V_{FAILSAFE} = 0\text{V}$	0.45	V	
			$0 \geq I_{OUT} \geq -400\mu\text{A}$, $V_{FAILSAFE} = V_{CC}$	2.7		
Differential Input High Threshold	V_{TL}	$V_{OUT} = 0.45\text{V}$, $I_{OUT} = -440\mu\text{A}$ (See Figure 1)	$R_s = 0$ (Note 3)	50	200	mV
			$R_s = 500$ (Note 3)		400	
Differential Input Low Threshold	V_{TL}	$V_{OUT} = 0.45\text{V}$, $I_{OUT} = 8\text{mA}$ (See Figure 1)	$R_s = 0$ (Note 3)	-200	-50	mV
			$R_s = 500$ (Note 3)		-400	
Hysteresis	V_H	$F_s = 0\text{V}$ or V_{CC} (See Figure 1)	45	140	mV	
Open Circuit Input Voltage	V_{IOC}			75	mV	
Input Capacitance	C_i			20	pF	
High Level Output Voltage	V_{OH}	$V_{ID} = 1\text{V}$, $I_{OUT} = -440\mu\text{A}$	2.7		V	
Low Level Output Voltage	V_{OL}	$V_{ID} = -1\text{V}$ (Note 4)	$I_{OUT} = 4\text{mA}$	0.4	V	
			$I_{OUT} = 8\text{mA}$	0.45		
Short Circuit Output Current	I_{OS}	Note 5	20	100	mA	
Supply current	I_{CC}	$4.75\text{V} \leq V_{CC} \leq 5.25\text{V}$		35	mA	
Input Current	I_{IN}	Other Inputs Grounded	$V_{IN} = +10\text{V}$	3.25	mA	
			$V_{IN} = -10\text{V}$	-3.25		

Note 3: R_s is a resistor in series with each input.

Note 4: Measure after 100 ms warm up (at 0°C).

Note 5: Only 1 output may be shorted at a time and then only for a maximum of 1 sec.

Note 6: The delays, either t_{PLH} or t_{PHL} , shall not vary from receiver to receiver by more than 35ns.

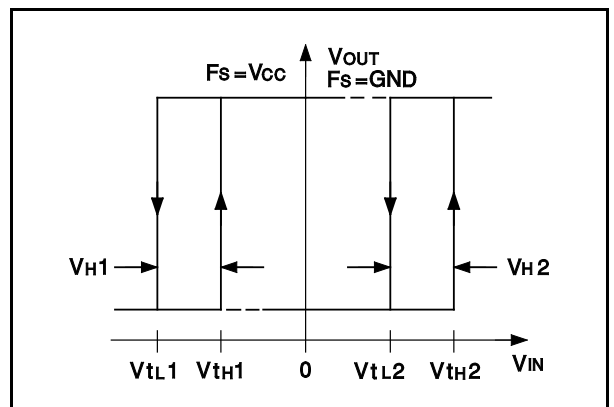


Figure 1. VTL, VTH, VH Definition

AC ELECTRICAL CHARACTERISTICS: $V_{CC} = 5\text{V} \pm 5\%$. $T_A = 0^\circ\text{C}$ to $+70^\circ\text{C}$, Figure 2 $T_A = T_J$.

PARAMETER	SYMBOL	TEST CONDITIONS	UC5181C		UNITS
			MIN	MAX	
Propagation Delay–Low to High	t_{PLH}	$C_L = 50\text{pF}$, $V_{IN} = \pm 500\text{mV}$ (Note 6)		120	ns
Propagation Delay–High to Low	t_{PHL}	$C_L = 50\text{pF}$, $V_{IN} = \pm 500\text{mV}$ (Note 6)		120	ns
Acceptable Input frequency	f_a	Unused Input Grounded, $V_{IN} = \pm 200\text{mV}$		5.0	MHz

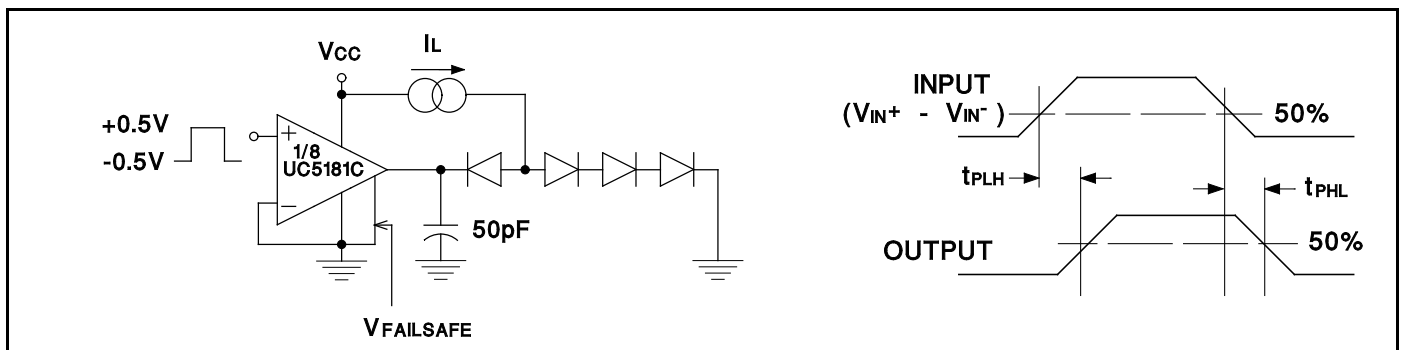


Figure 2. AC Test Circuit

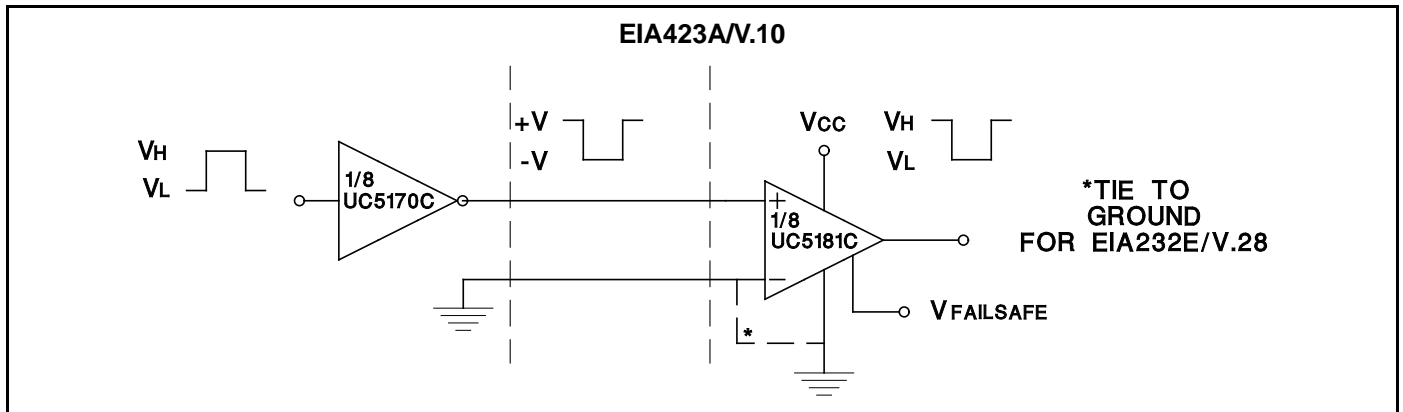
APPLICATIONS INFORMATION

Failsafe Operation

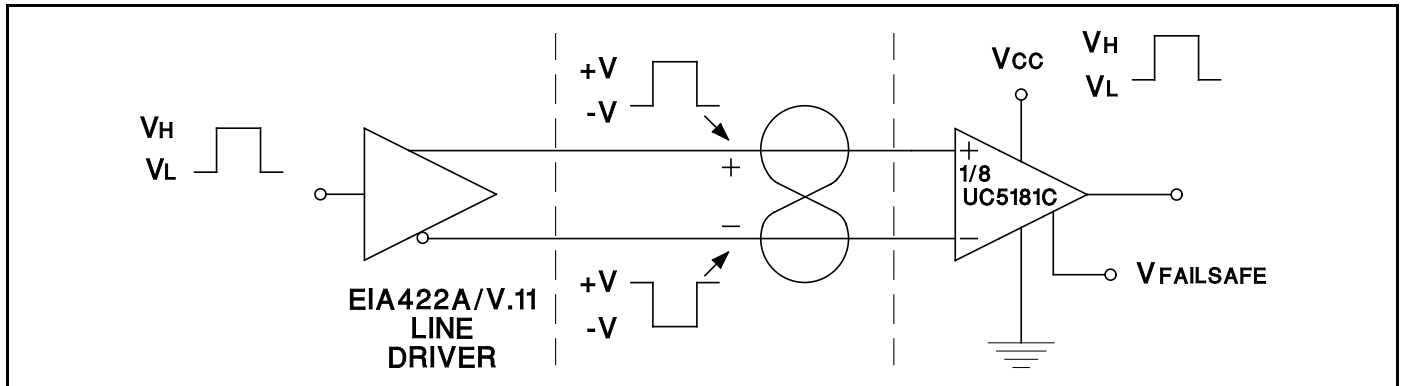
These devices provide a failsafe operating mode to guard against input fault conditions as defined in EIA422A and EIA423A standards. These fault conditions are (1) driver in power-off condition, (2) receiver not interconnected with driver, (3) open-circuited interconnecting cable, and (4) short-circuited interconnecting cable. If one of these four fault conditions occurs at the inputs of a receiver,

then the output of that receiver is driven to a known logic level. The receiver is programmed by connecting the failsafe input to VCC or ground. A connection to VCC provides a logic "1" output under fault conditions, while a connection to ground provides a logic "0". There are two failsafe pins (Fs1 and Fs2) on the UC5181C where each provides common failsafe control for four receivers.

EIA232E/V.28 / EIA423A/V.10 DATA TRANSMISSION



EIA422A/V.11 DATA TRANSMISSION



GENERAL LAYOUT NOTES

The drivers and receivers should be mounted close to the system common ground point, with the ground reference tied to the common point to reduce RFI/EMI.

Filter connectors or transzorbs should be used to reduce the RFI/EMI, and protecting the system from static (ESD), and electrical overstress (EOS). A filter connector or capacitor will reduce the ESD pulse by 90% typically. A cable dragged across a carpet and connected to a system can easily be charged to over 25,000 volts. This is a metal to metal contact when the cable is connected to the

system (no resistance), currents exceed 80 amps with less than a nanosecond rise time. A transzorb provides two functions, the device capacitance inherently acts as a filter capacitor, and the device clamps the ESD and EOS pulses which would pass through the capacitor and destroy the devices. The recommended transzorb for the UC5180C and the UC5181C is P6KE22CA.

* Transzorb is a trademark of General Semiconductor Industries.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
UC5181CQ	ACTIVE	PLCC	FN	28	37	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
UC5181CQTR	ACTIVE	PLCC	FN	28		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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